

05-03-2004



FORM PTO-1595

RECORDA

(Rev. 10/02)

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

Docket No.: 60188-852

4-28-04

PATENTS ONLY

102735597

To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Party(ies):

Kenji YONEDA

2. Name and address of receiving party(ies):

Name: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.

Address: 1006, Oaza Kadoma,
Kadoma-shi,
Osaka JAPAN 571-8501Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: April 23, 2004

Additional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application number(s) or patent number(s):

10833037

If the document is being filed together with a new application, the execution date of the application is: April 23, 2004

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT, WILL & EMERY

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)

\$40.00

☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number:

500417

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Michael E. Fogarty, 36,139

April 28, 2004

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet: 3

OMB No. 0651-0027 (exp. 6/30/2005)

04/30/2004 ECDPER 00000059 500417 10833037

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40.00 DA

PATENT
REEL: 015270 FRAME: 0582

Attorney Docket No. _____

A S S I G N M E N T

WHEREAS, **Kenji YONEDA** (hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in **METHOD FOR FABRICATING SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING SEMICONDUCTOR SUBSTRATE USED IN THE SEMICONDUCTOR DEVICE** for which the undersigned has (have):

- (a) filed an application for Letters Patent of the United States of America on _____ having Serial No. _____; or
- (b) executed an application for Letters Patent of the United States of America on the date(s) indicated below; and

WHEREAS, **Matsushita Electric Industrial Co., Ltd.** of **1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, Japan**

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto the Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to the application and any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to the Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

This Assignment has been executed by the undersigned on the date(s) indicated.

Date: April 23, 2004, *Kenji Yoneda*
Kenji YONEDA

Date: _____, _____

Date: _____, _____

Date: _____, _____

Date: _____, _____

Date: _____, _____

Date: _____, _____

Date: _____, _____